

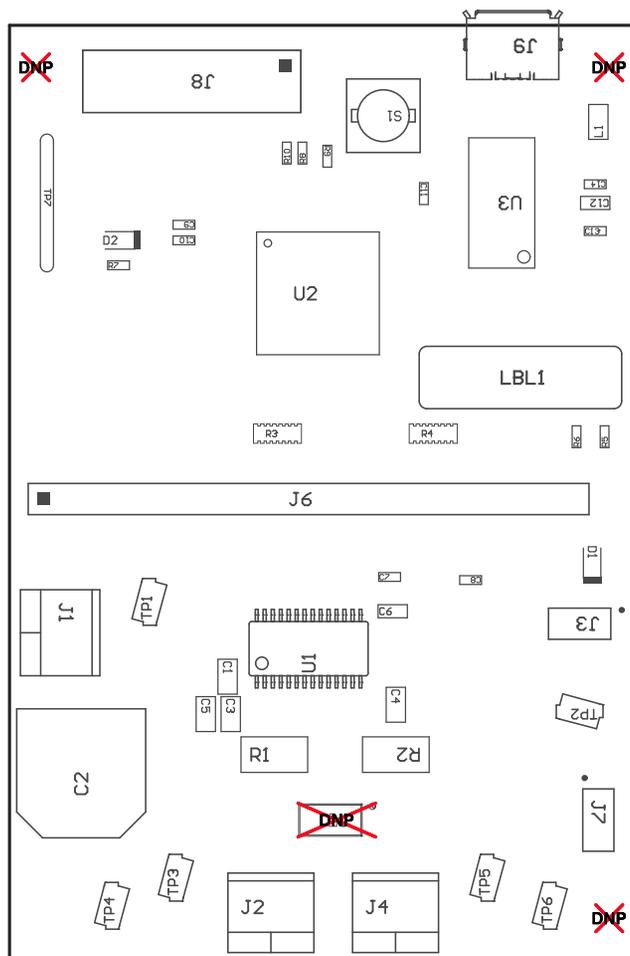
Z25 ■ Shorting plug TP7 shall be raised to minimum height of 250mils above PCB

Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

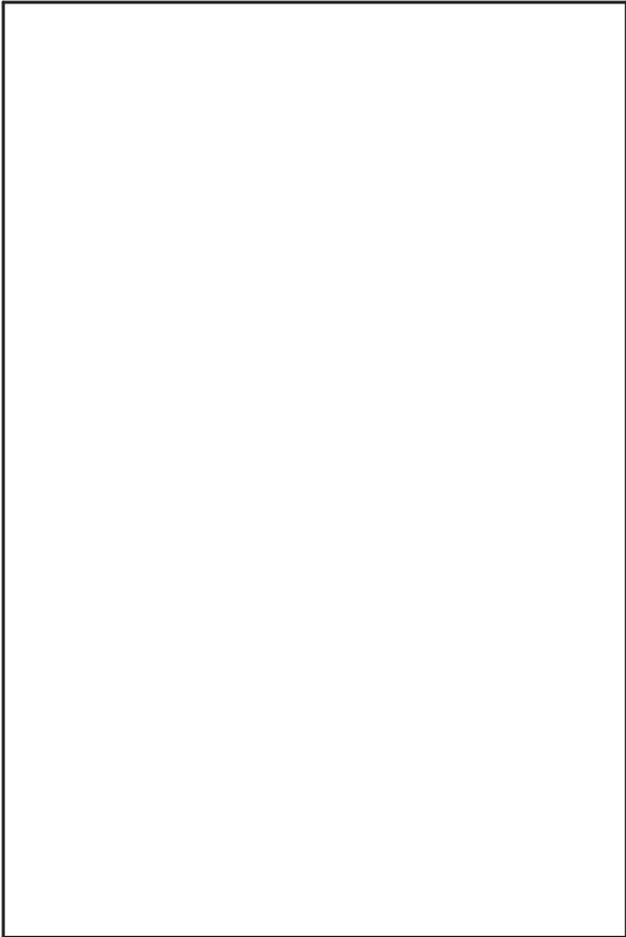
Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: 00830	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-00830		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/9/2015 10:29:54 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: 00830	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-00830		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/9/2015 10:29:54 AM	TEXAS INSTRUMENTS	

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